

ABSTRACT

An inventive electronic device includes a substrate, a bump of a first metal material provided on a surface of the substrate, a bonding film of a second metal material provided on a top surface of the bump for bonding the electronic device to an electrical connection portion of a second device, the second metal material having a lower melting point in an elemental state than an alloy of the first metal material and the second metal material, and a diffusion prevention film of a third metal material provided between the top surface of the bump and the bonding film as covering at least part of the top surface of the bump, the third metal material having a lower diffusion coefficient than the second metal material with respect to the first metal material.